

AMENDMENTS TO THE CLAIMS

This listing of claims replaces all prior versions of claims in the application.

1. (Cancelled)
2. (Currently Amended): A sheet peeling apparatus for peeling off a sheet being stuck on ~~a plate-like~~ an object using an adhesive tape, comprising:
a first peeling unit that pulls said adhesive tape along the direction across said sheet in a state stuck to the sheet to peel off the sheet at a predetermined peeling angle; and
a second peeling unit that pulls said adhesive tape in a state stuck to the end portion of said sheet to peel off the sheet at a peeling angle different from said peeling angle,
wherein said first and second peeling units are arranged to be selectively used.
3. (Currently Amended): A sheet peeling apparatus for peeling off a sheet being stuck to cover the surface of a semiconductor wafer ~~having a substantially disk-like shape~~ using an adhesive tape of a width narrower than the diameter of the sheet, comprising:
a first peeling unit that pulls said adhesive tape along the direction across said sheet in a state stuck to the sheet to peel off the sheet at a predetermined peeling angle; and
a second peeling unit that pulls said adhesive tape in a state stuck to the end portion of said sheet to peel off the sheet at a peeling angle different from said peeling angle,
wherein said first and second peeling units are arranged to be selectively used.

4. (Original): The sheet peeling apparatus according to claim 2 or 3, wherein said first peeling unit peels off said sheet in a direction substantially right angle or acute angle with respect to the surface of said plate-like object.

5. (Previously Presented): The sheet peeling apparatus according to claim 2 or 3, wherein said second peeling unit peels off said sheet at a peeling angle larger than the peeling angle by said first peeling unit.

6. (Cancelled)

7. (Currently Amended): A sheet peeling method of peeling off a sheet stuck on a ~~plate-like an~~ object using an adhesive tape, the method comprising:

a first peeling unit that pulls said adhesive tape along the direction across said sheet in a state stuck to the sheet to peel off the sheet at a predetermined peeling angle; and

a second peeling unit that pulls said adhesive tape in a state stuck to the end portion of said sheet to peel off the sheet at a peeling angle different from said peeling angle, wherein, said first and second peeling units are selectively used to peel off said sheet.

8. (Original): The sheet peeling method according to claim 7, wherein said first peeling unit peels off said sheet in the substantially right angle or acute angle direction with

respect to the surface of said plate-like object, and said second peeling unit peels off said sheet at a peeling angle larger than the peeling angle by said first peeling unit.

9. (New): The sheet peeling apparatus according to claim 2, wherein said object has a plate shape.

10. (New): The sheet peeling method apparatus to claim 3, wherein said semiconductor wafer has a disk shape.

11. (New): The sheet peeling method according to claim 7, wherein said object has a plate shape.